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United States Patent [19]
Shimazu

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[54] **WAFER BOAT FOR USE IN A SEMICONDUCTOR WAFER HEAT PROCESSING APPARATUS**

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[*] Notice: This patent is subject to a terminal disclaimer.

[**] Term: **14 Years**

[21] Appl. No.: **29/083,421**

[22] Filed: **Feb. 5, 1998**

[30] **Foreign Application Priority Data**

Aug. 20, 1997 [JP] Japan 9-65098

[51] **LOC (6) Cl.** **13-03**

[52] **U.S. Cl.** **D13/182**

[58] **Field of Search** D13/182; D15/144, D15/144.1, 119; 414/935-941, 217, 147; 437/247, 946; D6/407, 629

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[57] **CLAIM**

I claim the ornamental design for wafer boat for use in a semiconductor wafer heat processing apparatus, as shown and described.

DESCRIPTION

FIG. 1 a perspective view of a wafer boat for use in a semiconductor wafer heat processing apparatus.
FIG. 2 a front elevational view thereof.
FIG. 3 a cross-sectional view taken along line III—III in FIG. 2.
FIG. 4 a cross-sectional view taken along line IV—IV in FIG. 2.
FIG. 5 a rear elevational view thereof.
FIG. 6 a right side view thereof.
FIG. 7 a top plan view thereof; and,
FIG. 8 a bottom plan view thereof.

1 Claim, 3 Drawing Sheets

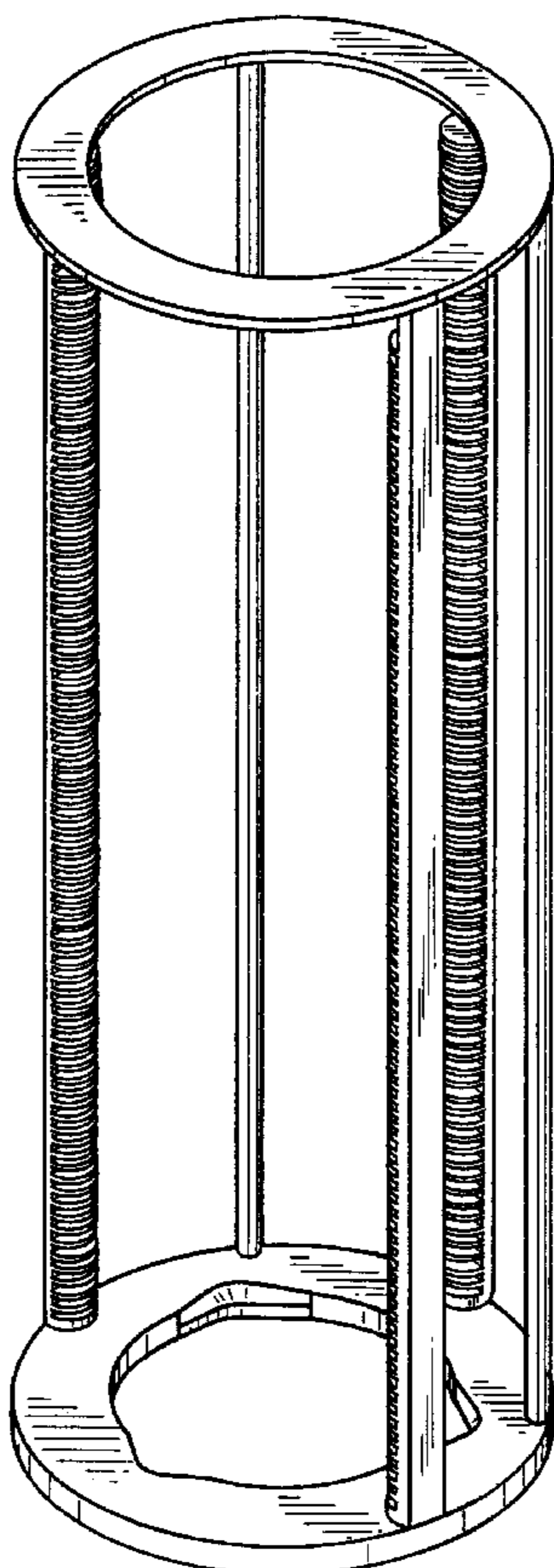


FIG. 1

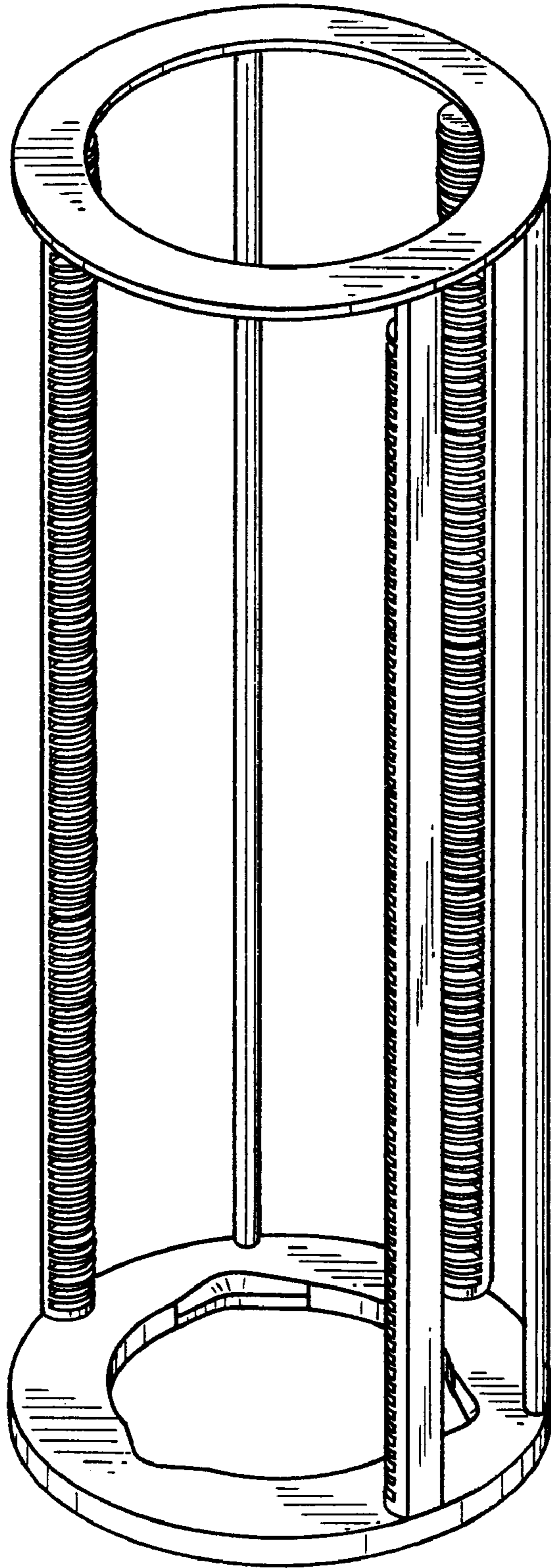


FIG. 2

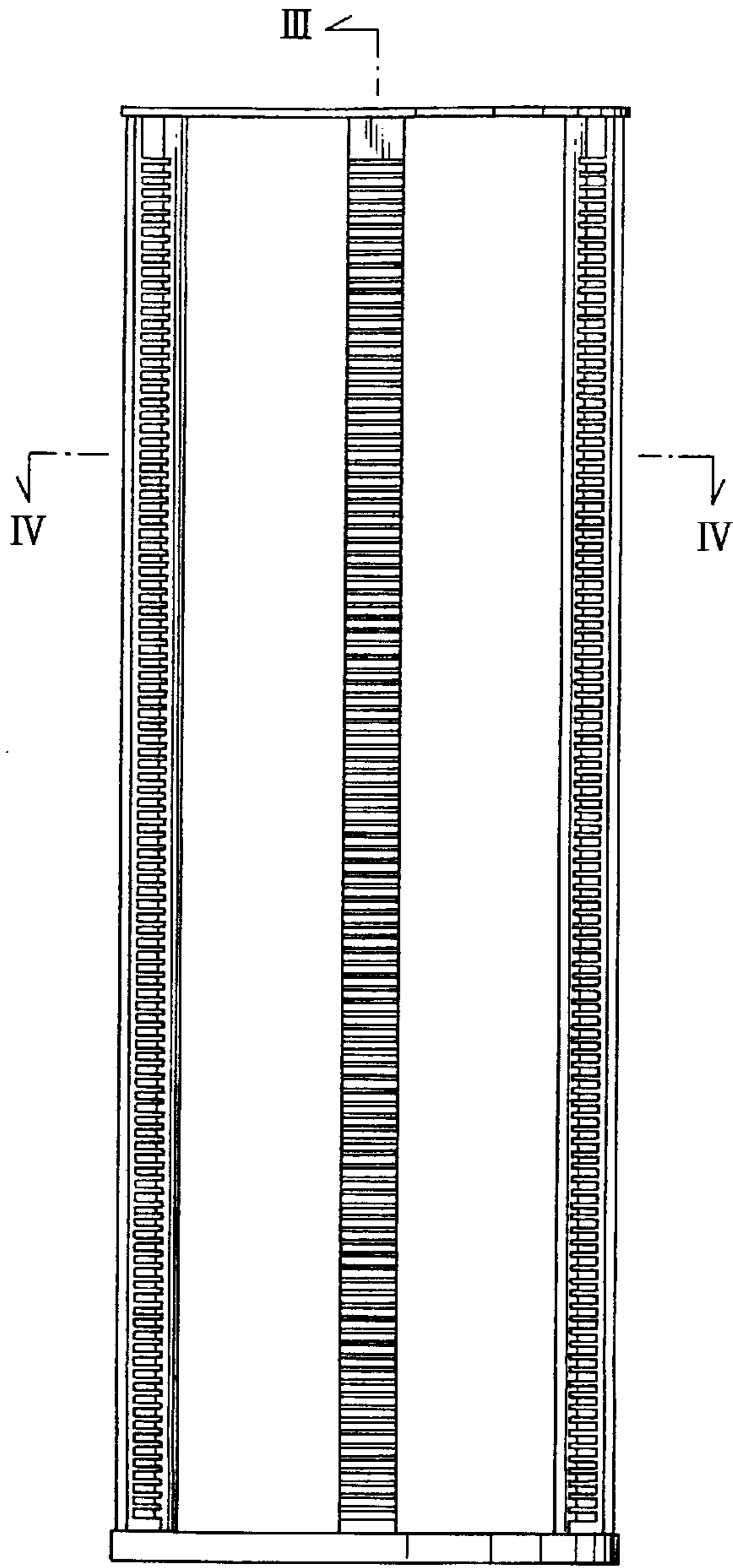


FIG. 3

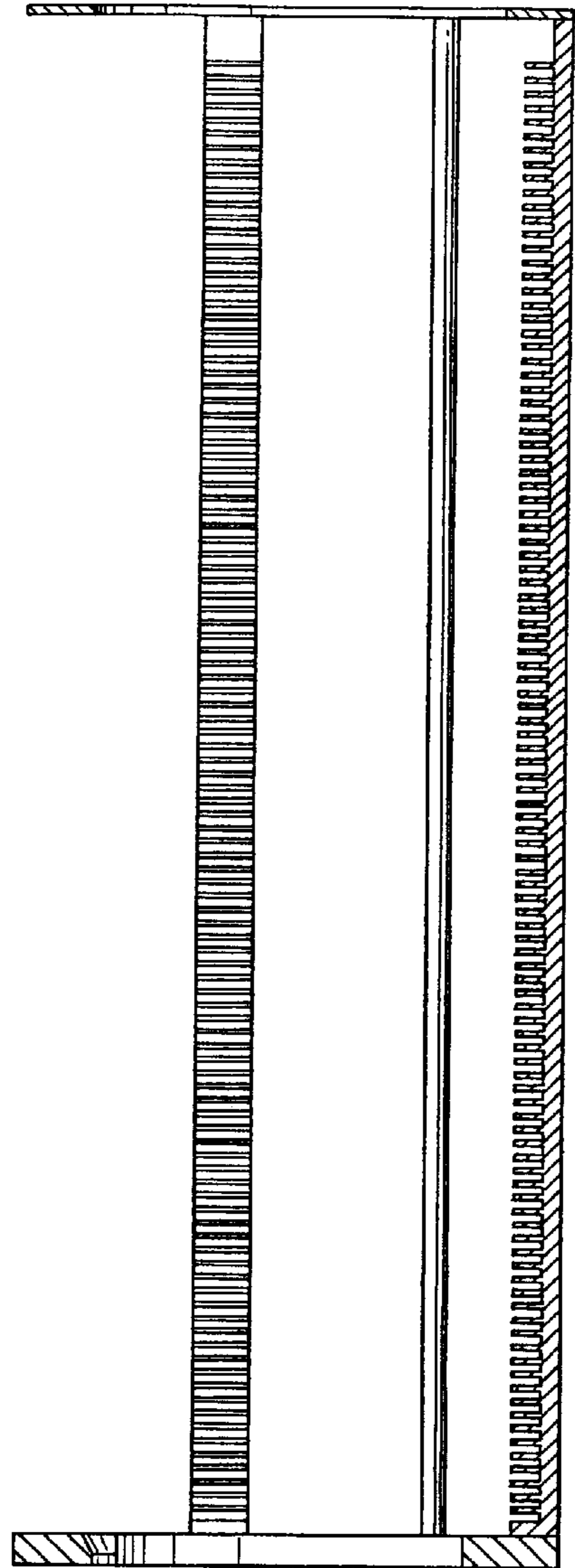


FIG. 4

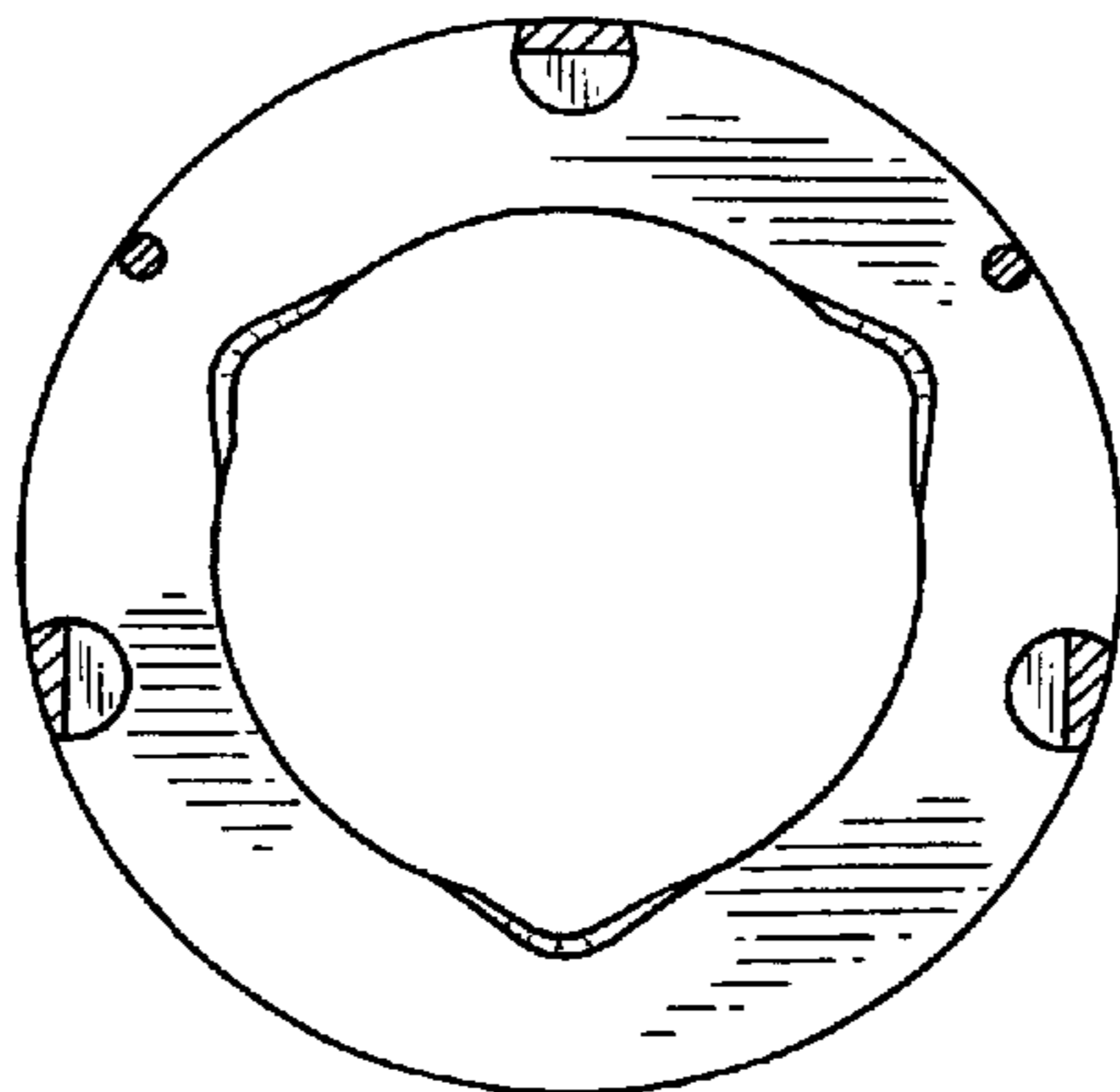


FIG. 5

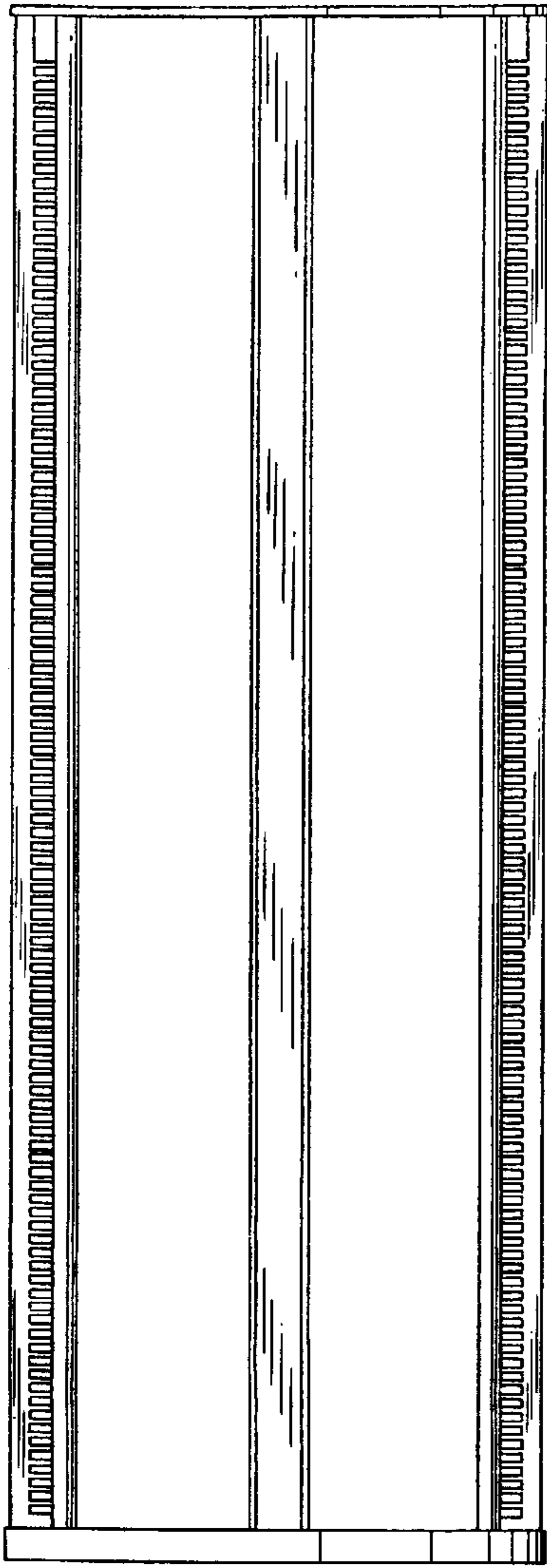


FIG. 6

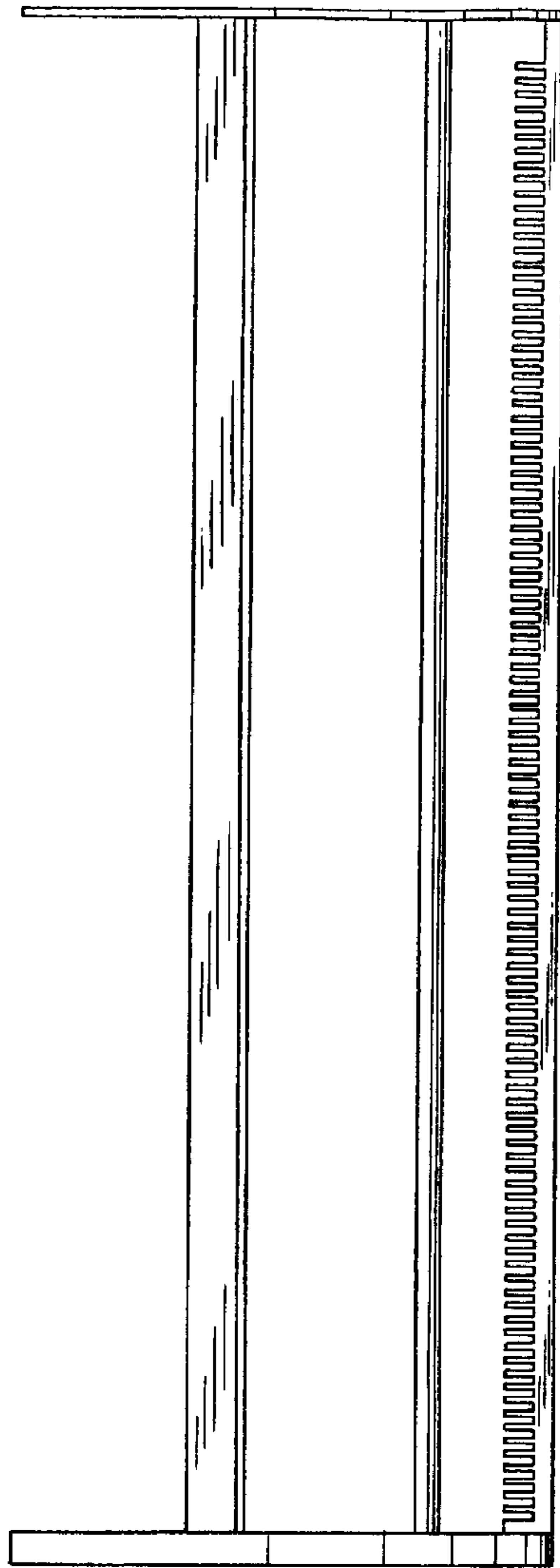


FIG. 7

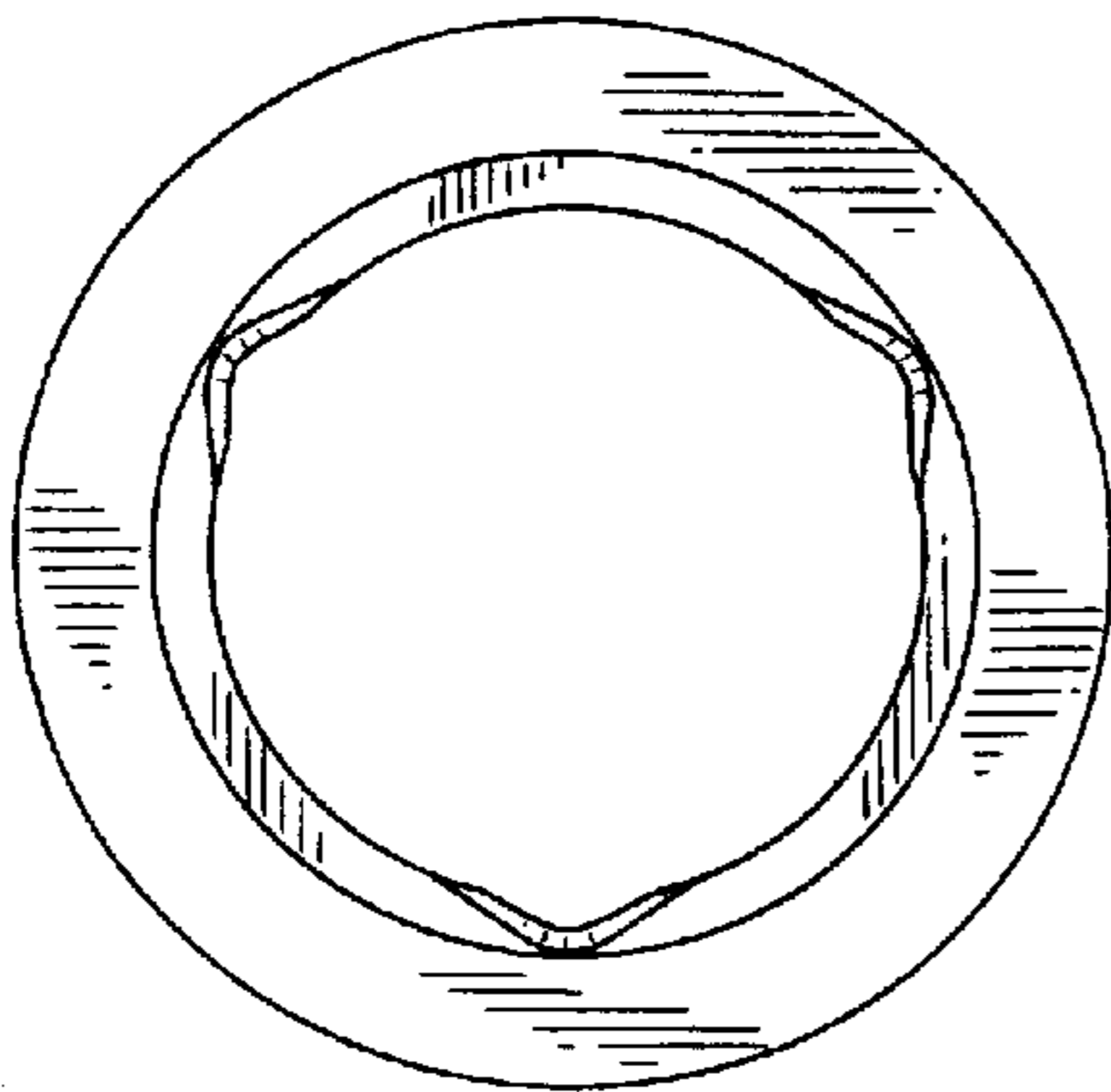


FIG. 8

